

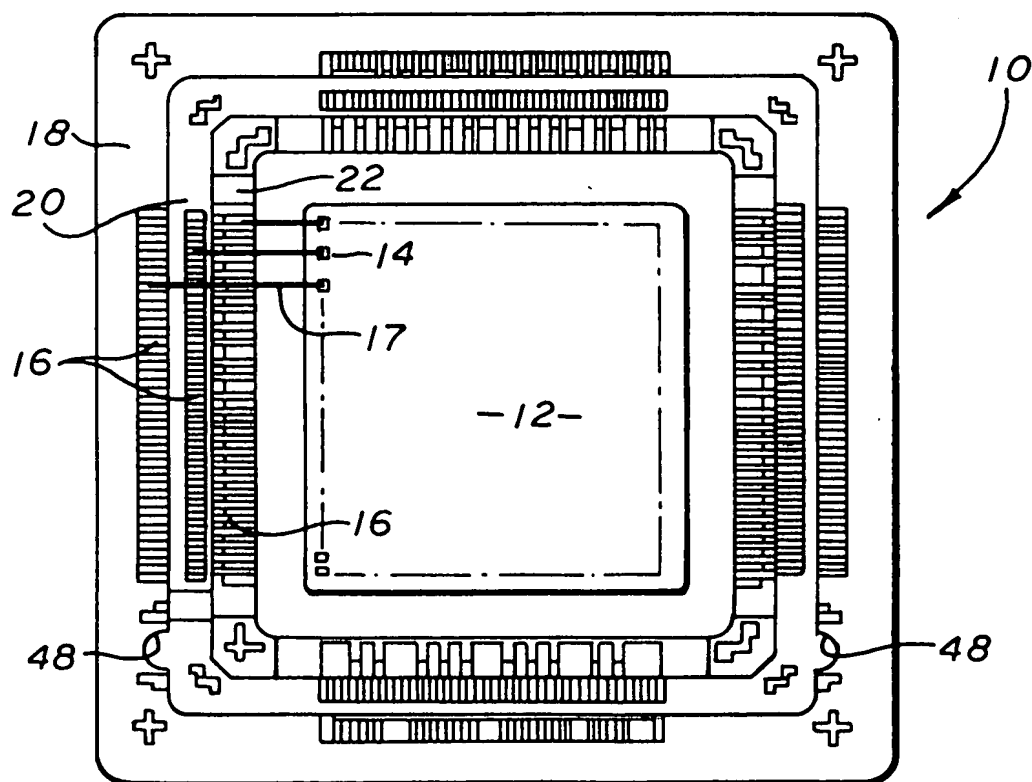
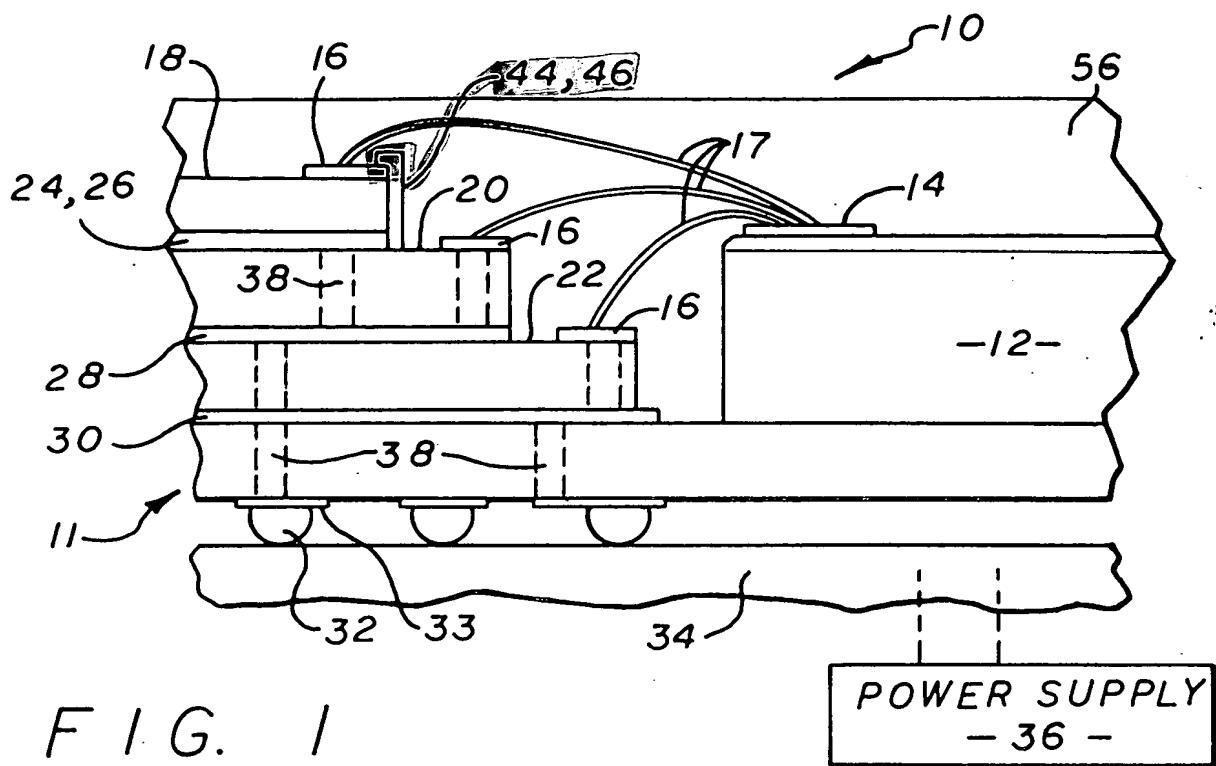
36  
--As shown in Figure 7, portions 54 of the conductive strips 44 and 46 may extend onto the first bond shelf 18 to connect to a bonding pad 16. The extra portions 54 may further anchor the conductive strips 44 and 46 to the housing and reduce the likelihood of delamination during the drilling process. The additional portions 54 can be formed by not masking the end of the first bond shelf 18 so that conductive material plates onto the shelf.

#### IN THE DRAWINGS

Applicant has amended Figures 1 and 4 as indicated by the highlighting in pink highlighter on the enclosed drawing sheets.

In Figure 1, the reference designators 44 and 46 ("44,46") are added to the conductive strip at the edge of the first bond shelf 18. Dashed lines between the pad 16 and busses 24,26 are deleted. The connection between the conductive strip 44,46 and the bond pad 16 is amended to be clearly shown in accordance with Figure 7.

In Figure 4, the end of busses 42, 24, are amended to more clearly show how bus 24 connects to strip 44 in accordance with Figure 1. The width of bus 26 is amended to more clearly show how bus 26 connects to strip 46. The connection between the conductive strip 44,46 and the bond pad 16 is amended to be clearly shown in accordance with Figure 7.





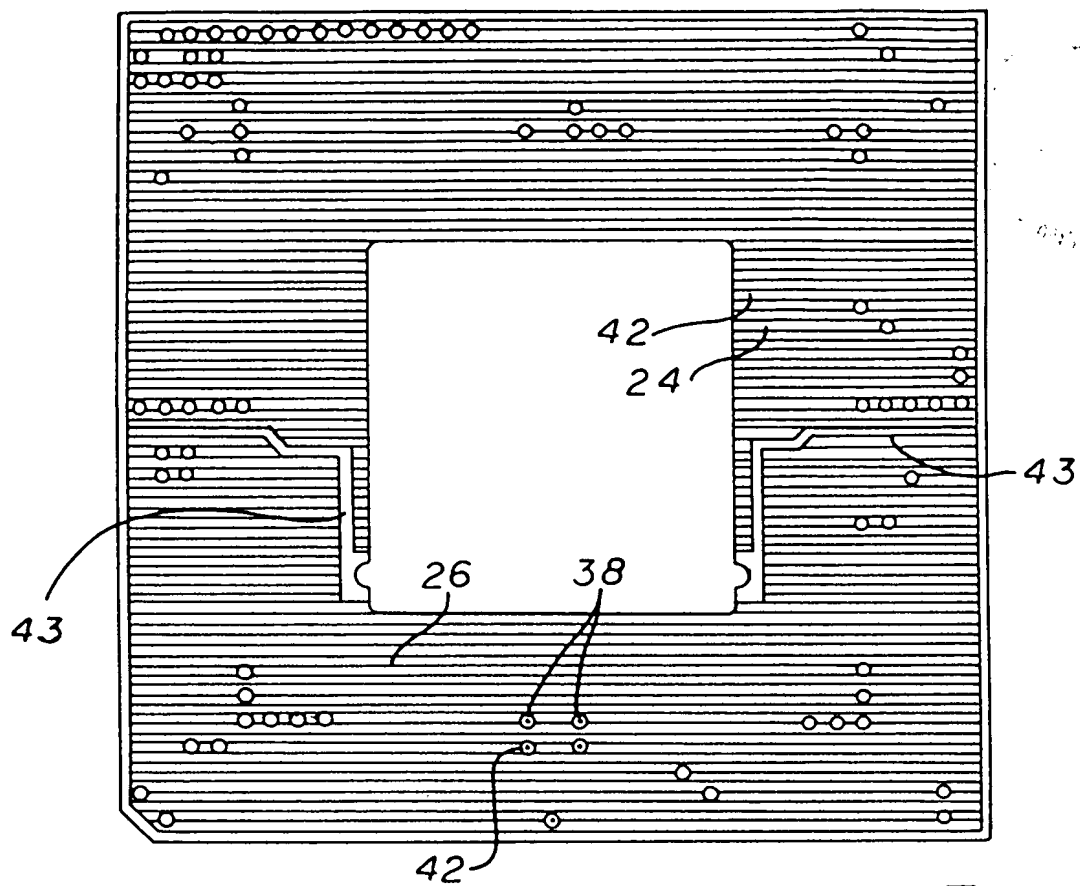


FIG. 3

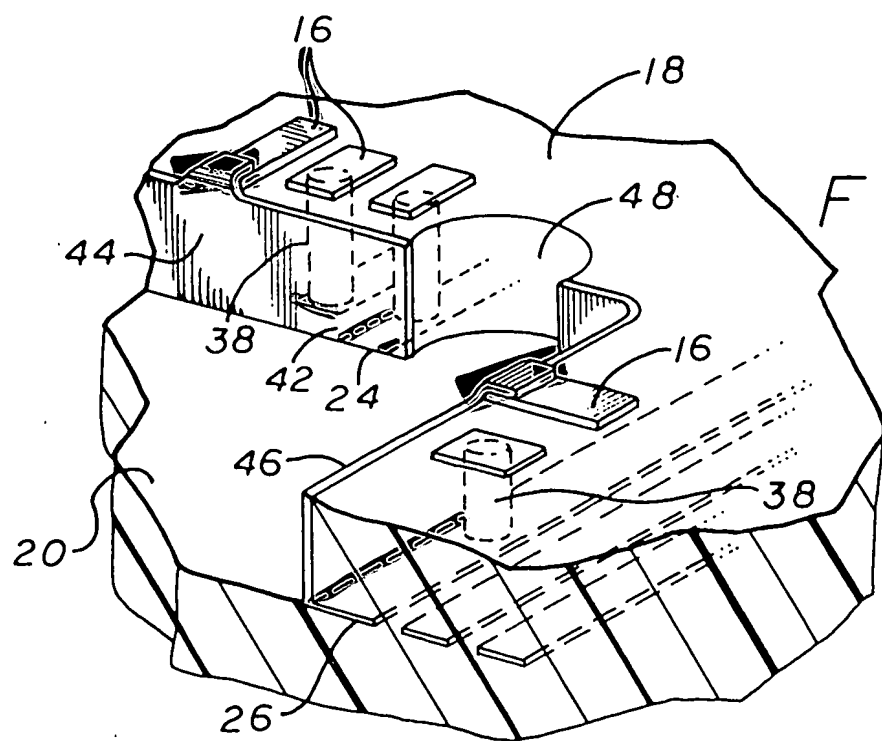


FIG. 4

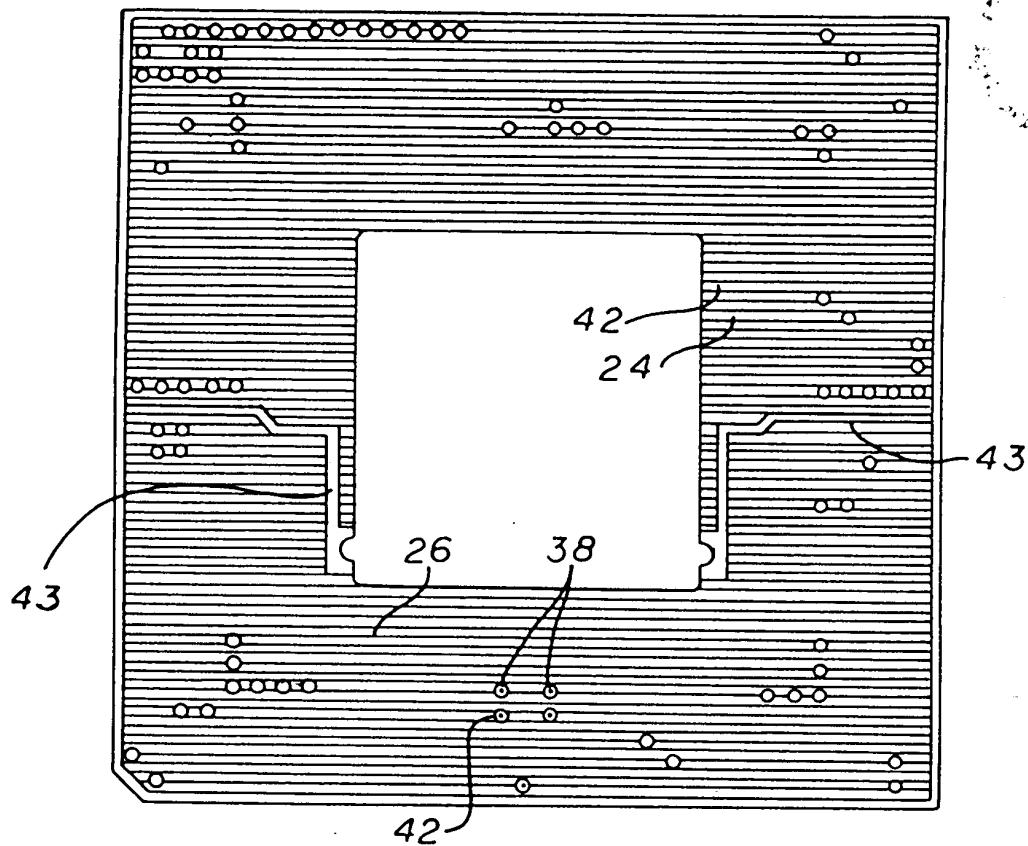


FIG. 3

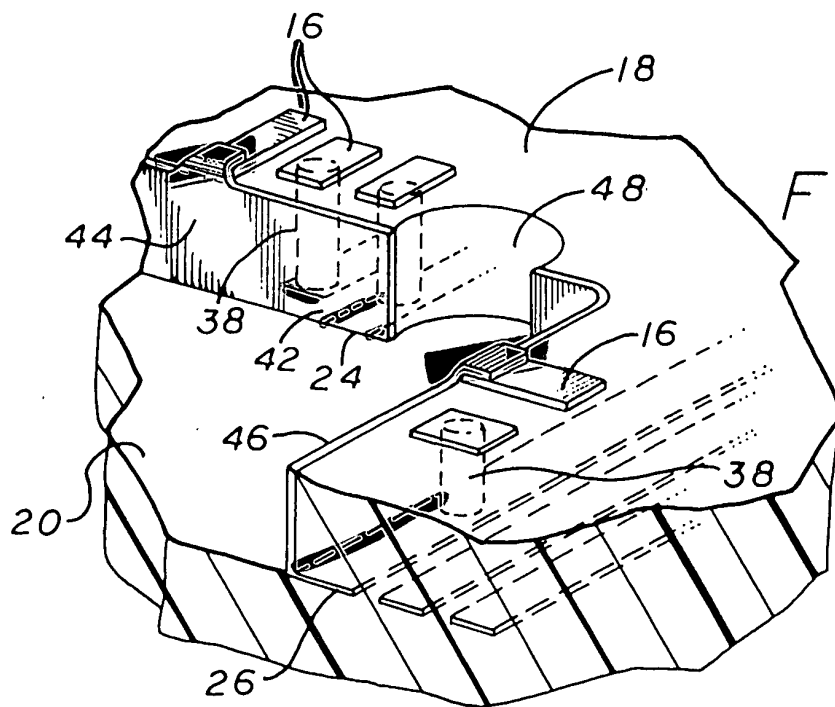


FIG. 4